ATTACHMENT: HIGH RELIABILITY ASSEMBLY FLOW

KEY:

▽ MANUFACTURING

〇 QUALITY CONTROL LOT INSPECTION

The following diagrams represent nominal process flows as of the date of issue. Specific details are available in LOGIC Devices Manufacturing Instructions.
HERMETIC
-55°C to +125°C

SAW
2ND OPTICAL INSPECTION
QC BUY-OFF
DIE ATTACH
QC BUY-OFF / MONITOR
WIRE BOND
3RD OPTICAL INSPECTION
QC BUY-OFF / MONITOR
BAKE
LID / CAP
PRE-SEAL BAKE
SEAL
STABILIZATION BAKE
MARKING
MARK CURE
TEMPERATURE CYCLE
CENTRIFUGE

CONTINUED
(Continued from previous page)

TRIM
FINE LEAK TEST
GROSS LEAK TEST
4TH OPTICAL INSPECTION
QC BUY-OFF / MONITOR
PACKING
PRE BURN-IN ELECTRICAL TEST = +25°C
PER LOGIC SPECIFICATION
BURN-IN
PER MIL-STD-883, METHOD 1015
POST BURN-IN ELECTRICAL TEST = +25°C
PER LOGIC SPECIFICATION
PDA VERIFICATION
5% FPA MAX
100% ELECTRICAL TEST T = +125°C
PER LOGIC SPECIFICATION
100% ELECTRICAL TEST T = -55°C
PER LOGIC SPECIFICATION
QC GROUP A, ELECTRICAL TEST T = +25°C
PER MIL-STD-883, METHOD 5005 SUBGROUPS 1,7,9. LTPD = 2
QC GROUP A, ELECTRICAL TEST T = +125°C
PER MIL-STD-883, METHOD 5005 SUBGROUPS 2, 8A, 10. LTPD = 2
CONTINUED
QC GROUP A, ELECTRICAL TEST
T = -55°C
PER MIL-STD-883, METHOD 5005, SUBGROUPS 3, 8B, 11
LTPD = 2 (B SUFFIX), LTPD = 10 (E SUFFIX)

100% EXTERNAL VISUAL INSPECTION
PER LOGIC SPECIFICATION

QC EXTERNAL VISUAL INSPECTION
PER LOGIC SPECIFICATION, AQL = 0.10%

TO INVENTORY

FINAL VISUAL INSPECTION
PER MIL-STD-883, METHOD 2009

FINISHED PRODUCT UNIT REPACKAGING
PER CUSTOMER SPECIFICATION IF DIFFERENT FROM LOGIC STANDARD PACKAGING

QC FINAL VISUAL INSPECTION
PER LOGIC SPECIFICATION

MARK PART NUMBER PER LOGIC OR CUSTOMER SPEC.

ELECTRICAL SAMPLE TEST
T = +25°C, AQL = 0.10%

FROM INVENTORY

QC PLANT CLEARANCE
PER MIL-STD-883, METHOD 2009

GROUPS A, B, C, D, E Attributes Data (When Required)

ISSUE CERTIFICATE OF COMPLIANCE

PACK AND SHIP

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